

Catalog # 13-0050 Aluminum chloride, anhydrous (99.99+%-Al) PURATREM

AlCl₃

Catalysis Applications

AlCl₃ is a typical Lewis-acid catalyst for used in organic synthesis

Technical Notes:

1. Catalyst for regiospecific benzoylation of electron-deficient *N*-heterocycles with Methylbenzenes via a Minisci-type reaction
2. Used in transition-metal-free deacylative cleavage of unstrained C(sp³)–C(sp²) Bonds to generate aryl and aliphatic nitriles from ketones and aldehydes
3. Catalyst for microwave-assisted alcoholysis of furfural alcohol into alkyl levulinates
4. Catalyst for the transition metal- and cyanide-free one-step direct transformation of methylarenes into pharmaceutical-oriented aryl nitriles
5. Catalyst for the conversion of glucose to 5-hydroxymethylfurfural (HMF) in NaCl-H₂O/THF
6. Used in Lewis-acid-catalyzed reactions of 2-substituted cyclopropane 1,1-dicarboxylates with thioketones
7. Catalyst used for the synthesis of benzofurans and 4,5,6,7-tetrahydrobenzofurans from acrolein dimer and 1,3-dicarbonyls
8. Catalyst used in ring-opening reactions of donor-acceptor cyclobutanes with electron-rich arenes, thiols, and selenols
9. Catalyst for the synthesis of highly substituted phenols and benzenes with complete regiochemical control
10. Catalyst for the C-H phosphination of benzene

	Tech Note (1) Ref. (1)
	Tech Note (2) Ref. (2)
	Tech Note (3) Ref. (3)
	Tech Note (4) Ref. (4)

<p>$\text{R}^1\text{C}(\text{CO}_2\text{Me})_2 + \text{R}^2\text{C}=\text{X}\text{R}^3 \xrightarrow[\text{DCM, rt}]{\text{AlCl}_3} \text{R}^1\text{CH}_2\text{CH}(\text{CO}_2\text{Me})\text{CH}_2\text{XCH}(\text{CO}_2\text{Me})\text{R}^2\text{R}^3$</p> <p>X = S, Se</p>	Tech Note (5) Ref. (5)
<p>$\text{O}=\text{C}(\text{H})(\text{O})\text{C}_2\text{H}_4\text{CHO} + \text{R}^1\text{C}(=\text{O})\text{CH}_2\text{C}(=\text{O})\text{R}^2 \xrightarrow[\text{MeNO}_2, 80^\circ\text{C}, 6\text{ h}]{\text{AlCl}_3; \text{NBS}} \text{O}=\text{C}(\text{H})(\text{O})\text{C}_2\text{H}_4\text{C}(\text{R}^1)=\text{C}(\text{O})\text{R}^2$</p>	Tech Note (6) Ref. (6)
<p>$\text{R}^1\text{C}(\text{CO}_2\text{Me})_2 - \text{C}_4\text{H}_3 + \text{X}-\text{H} \xrightarrow[\text{DCM, } 0^\circ\text{C}]{\text{AlCl}_3/\text{X}-\text{H}} \text{R}^1\text{C}(\text{CO}_2\text{Me})_2 - \text{C}_6\text{H}_4\text{CH}_2\text{CH}(\text{X})\text{CH}_2\text{CO}_2\text{Me}$</p> <p>X = Ar, Ph, t-Bu, S, Se</p>	Tech Note (7) Ref. (7)
<p>$\text{HO}-\text{C}_6\text{H}_3(\text{R}^1)=\text{C}(\text{R}^2)-\text{O}-\text{C}(=\text{O})-\text{R}^3 + \text{R}^5-\text{C}(=\text{O})-\text{CH}=\text{C}(\text{R}^4)\text{R}^6 \xrightarrow[\text{BHT, } 150^\circ\text{C}]{\text{AlCl}_3; o-\text{C}_6\text{H}_4\text{Cl}_2} \text{R}^1-\text{C}_6\text{H}_3(\text{R}^2)=\text{C}(\text{OH})-\text{C}(\text{R}^3)-\text{C}_6\text{H}_3(\text{R}^5)=\text{C}(\text{R}^6)$</p>	Tech Note (8) Ref. (8)
<p>$\text{C}_6\text{H}_6 \xrightarrow[\text{PCl}_3]{\text{AlCl}_3} \text{C}_6\text{H}_5-\text{P}(\text{Cl})_2$</p>	Tech Note (9) Ref. (9)

References:

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CVD/ALD Applications

Thermal Behavior:

- Sublimation at 180°C
- Decomposition at 262°C

Technical Notes:

1. ALD precursor used for Al thin film deposition

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.

Al	ALD	95°C	-	AlH ₂ (^t BuN)(CH ₂) ₂ (NMe ₂)	140°C	1
Al ₂ O ₃	ALD	-	0.75 Torr	Al(OEt) ₃	400°C	2
	ALD	80°C	0.75 Torr	Al(O <i>i</i> Pr) ₃	150-375°C	3
	ALD	-	-	H ₂ O	300-800°C	4
	ALD	-	0.75 Torr	H ₂ O	250-300°C	5
	ALD	100°C	0.5 Torr		200°C	6
	ALD	100°C	-	O ₃	300-450°C	7
Nb ₂ O ₅ :Al ₂ O ₃	ALD	99°C	0.75 Torr	Nb(OEt) ₅ , H ₂ O	300°C	8
TiO ₂ :Al ₂ O ₃	ALD	70°C	0.75 Torr	TiCl ₄ , H ₂ O	80-250°C	9
AlN	ALD	140°C	0.6 Torr	NH ₃	500-550°C	10

References:

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